



SOT1263

Microlead ultra small surface-mounted plastic package; 3 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOT1263
Package type industry code	SOT1263
Package style descriptive code	USON (ultra thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	---
Mounting method type	S (surface mount)
Issue date	22-3-2011

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		0.75	-	0.8	0.85	mm
E	package width		0.55	-	0.6	0.65	mm
A	seated height		0.34	-	0.37	0.4	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	3	-	



2. Package outline

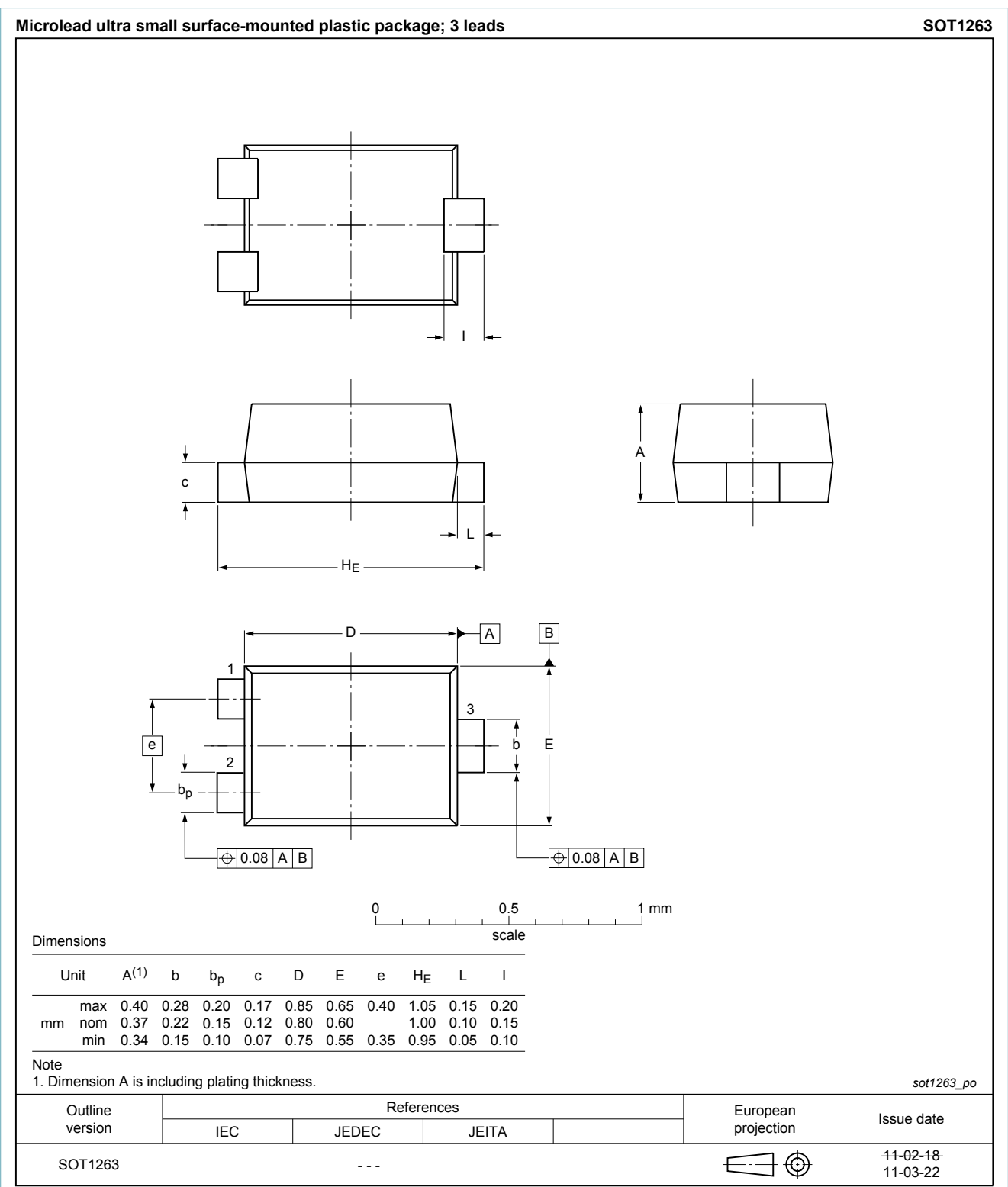


Fig. 1. Package outline SOT1263

3. Soldering

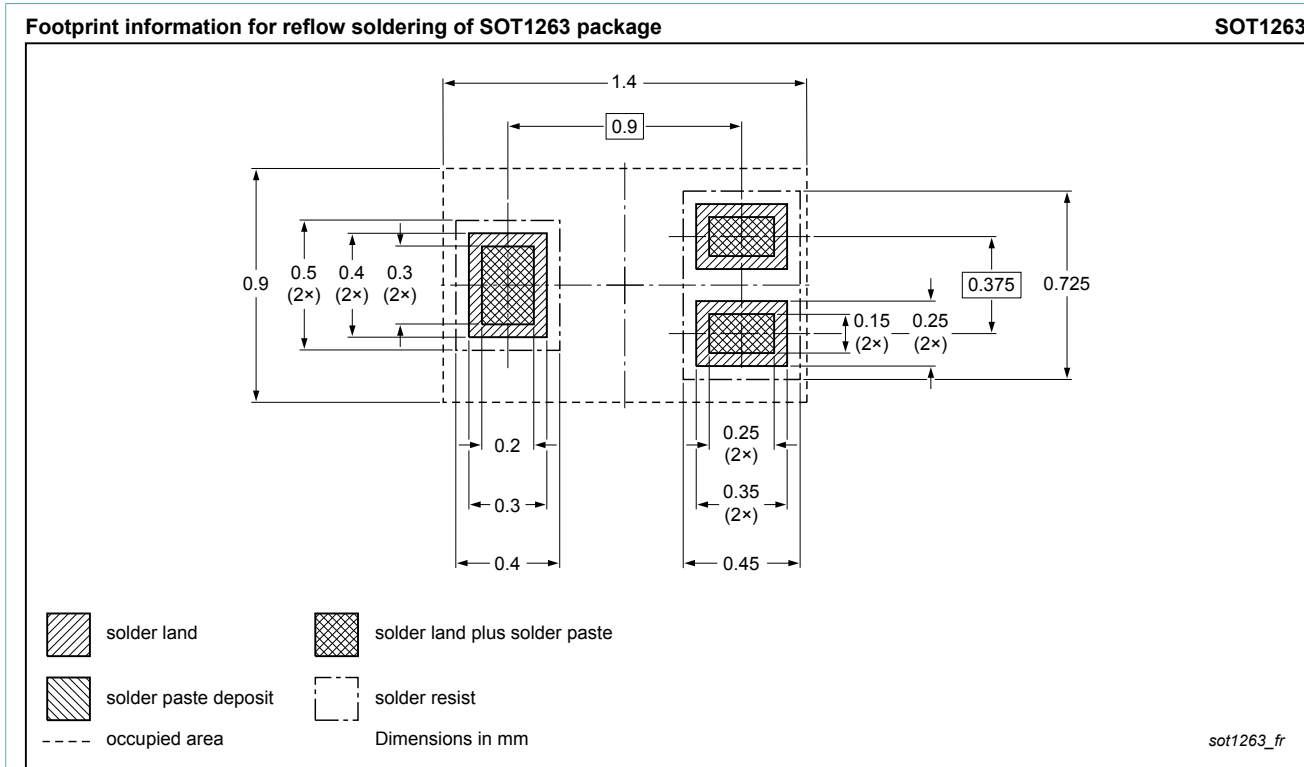


Fig. 2. Reflow soldering footprint for SOT1263

4. Legal information

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